



**SPECIFICATIONS:**

- ELECTRICAL CHARACTERISTICS:
  - RATING: 36V MAX.
  - CONTACT RESISTANCE: 30mΩ MAX (INITIAL).
- MECHANICAL CHARACTERISTICS:
  - INSERTION FORCE: 3.0KGF MAX
  - WITHDRAWAL FORCE: 0.3KGF MIN
  - LIFE TEST: 10,000 CYCLES MIN.
  - PACKAGING: TAPE & REEL
  - TO CONFORM TO THE SINGATRON HSF SPECIFICATION.
  - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT
  - HALOGEN PRODUCT IDENTIFICATION LABEL ON PACKAGING
  - FOR REFLOW SOLDERING LEAD-FREE PROCESS.
  - SOLDER HEAT RESISTANCE REFLOW SOLDERING 260°C 10SECS.
  - DATE CODE: YMMDD



G	COVER	1	SUS		
F	BODY	1	THERMOPLASTIC HIGH TEMP	BLACK COLOR	
E	RING SPRING B	1	COPPER ALLOY 0.2t	GOLD FLASH	
D	RING SPRING A	1	COPPER ALLOY 0.2t	GOLD FLASH	
C	TIP SPRING	1	COPPER ALLOY 0.2t	Gold flash on contact area and solder fill over Nickel plated	
B	GROUND	1	COPPER ALLOY 0.2t	GOLD FLASH	
A	EARTH	1	COPPER ALLOY 0.2t	GOLD FLASH	
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR	

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.  
信亨企業股份有限公司

3.5Ø PHONE JACK

TITLE	3.5Ø PHONE JACK
DWN	UNW020213
CHKD	ZZ 20101010
APVD	UNW 20120103
PART NO.	2SIJ2271-008111
SCALE	6:1
UNIT	mm
SIZE	A3
SHEET	10F1
REV.	D

CUSTOMER COPY

REV.	ECN NO. OR DESCRIPTION	REVISED	DATE
B	ECN:C100325 MODIFY POSITION	BILLY	2010.08.17
C	ECR:C110195Modify Earth	LONGJIANG	2011.08.09
D	ECN:C110387 Modify plating	LONGJIANG	2012.01.03

